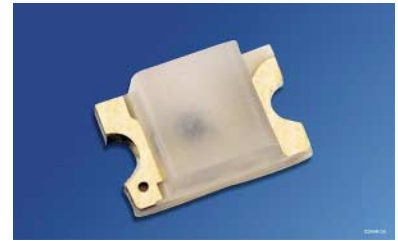


CHIPLED

LG R971



Besondere Merkmale

- **Gehäusotyp:** 0805
- **Besonderheit des Bauteils:** extrem kleine Bauform 2,0 mm x 1,25 mm x 0,8 mm
- **Wellenlänge:** 570 nm (grün)
- **Abstrahlwinkel:** extrem breite Abstrahlcharakteristik (160°)
- **Technologie:** GaP
- **optischer Wirkungsgrad:** 2,5 lm/W
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 8 mm Gurt mit 4000/Rolle, ø180 mm

Anwendungen

- Informationsanzeigen im Innenbereich
- optischer Indikator
- Flache Hinterleuchtung (LCD, Handy, Schalter, Display)
- Spielsachen

Features

- **package:** 0805
- **feature of the device:** extremely small package 2.0 mm x 1.25 mm x 0.8 mm
- **wavelength:** 570 nm (green)
- **viewing angle:** extremely wide (160°)
- **technology:** GaP
- **optical efficiency:** 2.5 lm/W
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 8 mm tape with 4000/reel, ø180 mm

Applications

- indoor displays
- optical indicators
- flat backlighting (LCD, cellular phones, switches, displays)
- toys

Typ	Emissions- farbe	Farbe der Lichtaustritts- fläche	Lichtstärke	Lichtstrom	Bestellnummer
Type	Color of Emission	Color of the Light Emitting Area	Luminous Intensity $I_F = 20 \text{ mA}$ $I_V (\text{mcd})$	Luminous Flux $I_F = 20 \text{ mA}$ $\Phi_V (\text{mlm})$	Ordering Code
LG R971	green	colorless diffused	7.1 ... 28.0	53 (typ.)	Q65110P5179

*Anm.: Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur zwei Gruppen besteht. Einzelne Gruppen sind nicht erhältlich.
In einer Verpackungseinheit / Gurt ist immer nur eine Gruppe enthalten.*

*Note: The standard shipping format for serial types includes a lower or upper family group of 2 groups. Individual groups are not available.
No packing unit / tape ever contains more than one luminous intensity group.*

Grenzwerte
Maximum Ratings

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebstemperatur Operating temperature range	T_{op}	– 30 ... + 85	°C
Lagertemperatur Storage temperature range	T_{stg}	– 40 ... + 85	°C
Sperrschichttemperatur Junction temperature	T_j	+ 95	°C
Durchlassstrom Forward current	I_F	25	mA
Stoßstrom Surge current $t_p = 10 \mu s, D = 0.1$	I_{FM}	0.1	A
Sperrspannung ¹⁾ Reverse voltage	V_R	12	V
Leistungsaufnahme Power consumption	P_{tot}	65	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient Sperrschicht/Löt看 Junction/solder point Montage auf PC-Board FR 4 (Padgröße $\geq 5 \text{ mm}^2$) mounted on PC board FR 4 (pad size $\geq 5 \text{ mm}^2$)	$R_{th JA}$ $R_{th JS}$	800 450	K/W K/W

¹⁾ für kurzzeitigen Betrieb geeignet / suitable for short term application

Kennwerte ($T_A = 25\text{ °C}$)

Characteristics

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge des emittierten Lichtes (typ.) Wavelength at peak emission $I_F = 20\text{ mA}$	λ_{peak}	572	nm
Dominantwellenlänge ¹⁾ (typ.) Dominant wavelength ¹⁾ $I_F = 20\text{ mA}$	λ_{dom}	570	nm
Spektrale Bandbreite (typ.) Spectral bandwidth $I_F = 20\text{ mA}$	$\Delta\lambda$	30	nm
Abstrahlwinkel bei 50 % I_V (Vollwinkel) (typ.) Viewing angle at 50 % I_V	2ϕ	160	Grad deg.
Durchlassspannung ²⁾ (typ.) Forward voltage ²⁾ (max.) $I_F = 20\text{ mA}$	V_F V_F	2.2 2.5	V V
Sperrstrom (typ.) Reverse current (max.) $V_R = 12\text{ V}$	I_R I_R	0.02 100	μA μA
Temperaturkoeffizient von λ_{peak} (typ.) Temperature coefficient of λ_{peak} $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{peak}}}$	0.10	nm/K
Temperaturkoeffizient von λ_{dom} (typ.) Temperature coefficient of λ_{dom} $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{dom}}}$	0.06	nm/K
Temperaturkoeffizient von V_F (typ.) Temperature coefficient of V_F $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	TC_V	- 1.4	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 20\text{ mA}$	η_{opt}	2.5	lm/W

¹⁾ Wellenlängengruppen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 1\text{ nm}$ ermittelt.
Wavelength groups are tested at a current pulse duration of 25 ms and a tolerance of $\pm 1\text{ nm}$.

²⁾ Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von $\pm 0,1\text{ V}$ ermittelt.
Voltages are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.1\text{ V}$.

Helligkeits-Gruppierungsschema
Luminous Intensity Groups

Lichtgruppe Luminous Intensity Group	Lichtstärke Luminous Intensity I_V (mcd)	Lichtstrom Luminous Flux Φ_V (lm)
K	7.10 ... 11.20	25.0 (typ.)
L	11.20 ... 18.00	40.0 (typ.)
M	18.00 ... 28.00	65.0 (typ.)

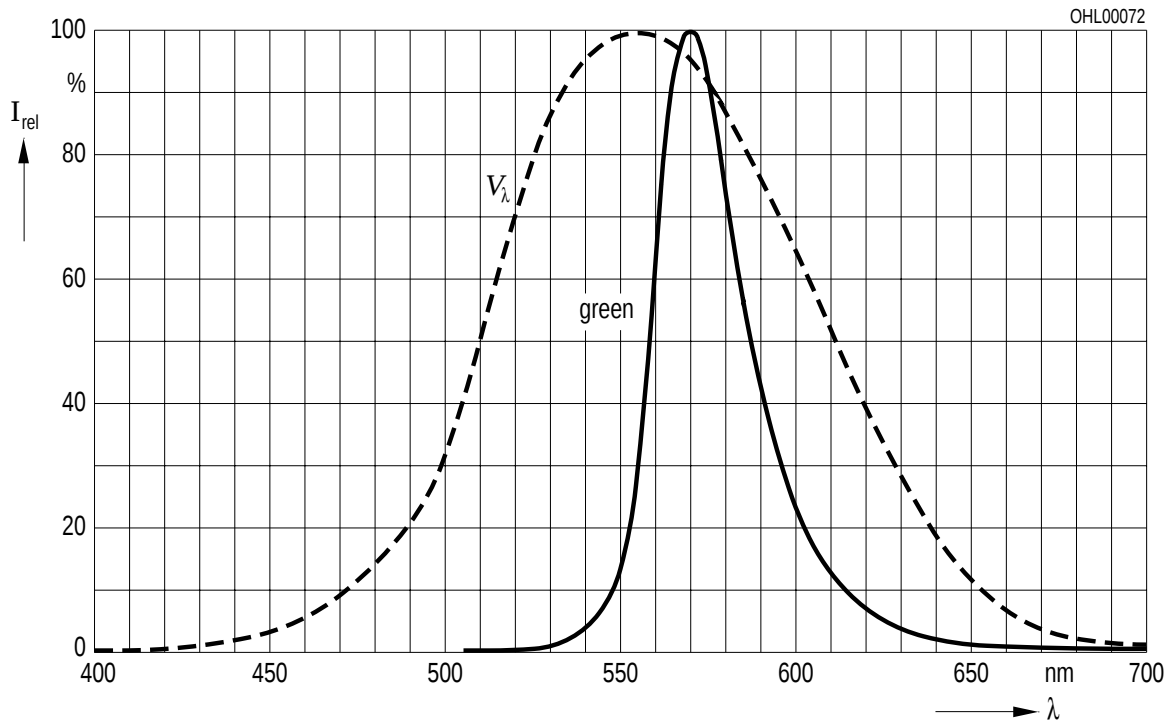
Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 11\%$ ermittelt.
 Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of $\pm 11\%$.

Relative spektrale Emission $I_{\text{rel}} = f(\lambda)$, $T_A = 25\text{ °C}$, $I_F = 20\text{ mA}$

Relative Spectral Emission

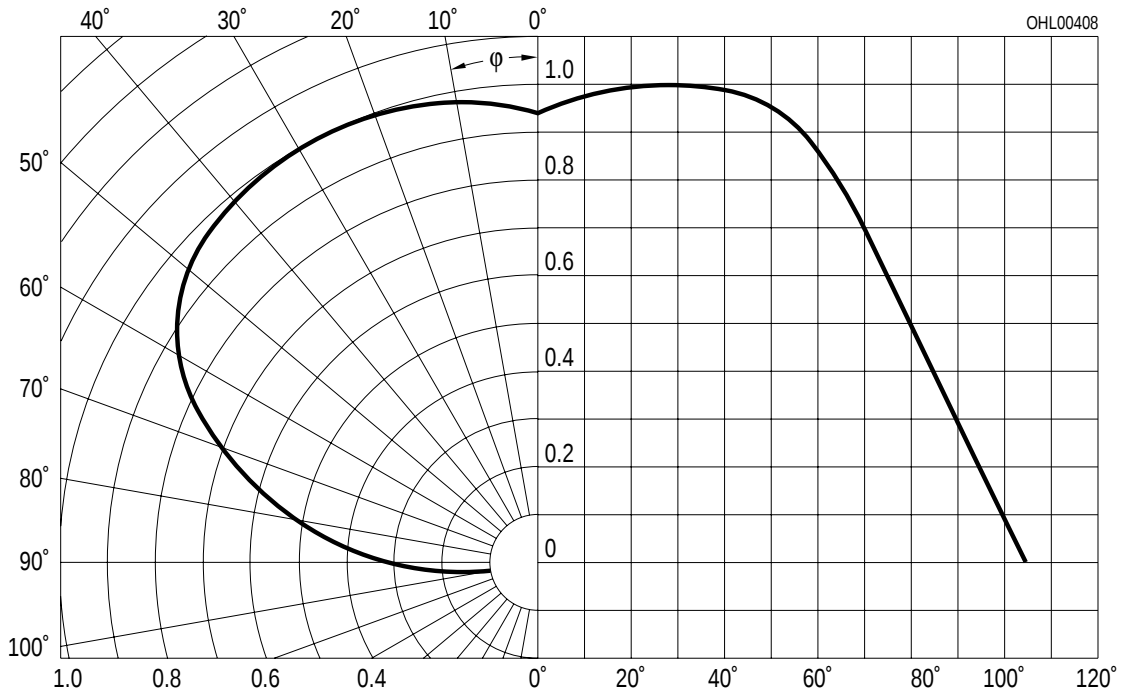
$V(\lambda)$ = spektrale Augenempfindlichkeit

Standard eye response curve



Abstrahlcharakteristik $I_{\text{rel}} = f(\varphi)$

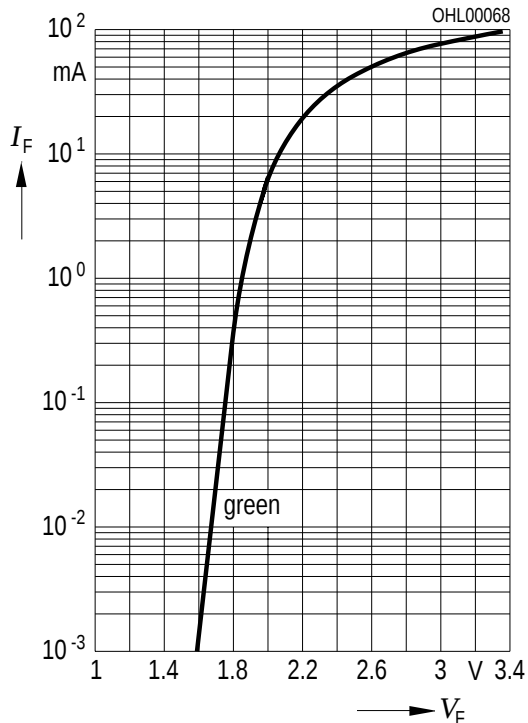
Radiation Characteristic



Durchlassstrom $I_F = f(V_F)$

Forward Current

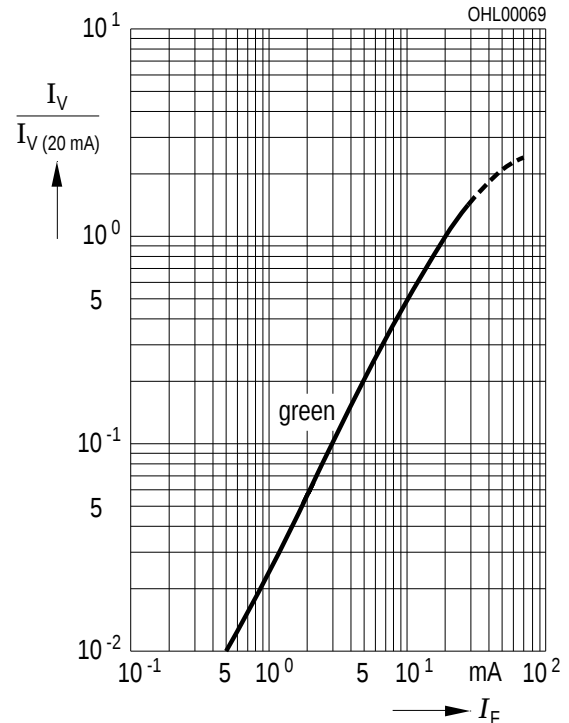
$T_A = 25\text{ °C}$



Relative Lichtstärke $I_V/I_{V(20\text{ mA})} = f(I_F)$

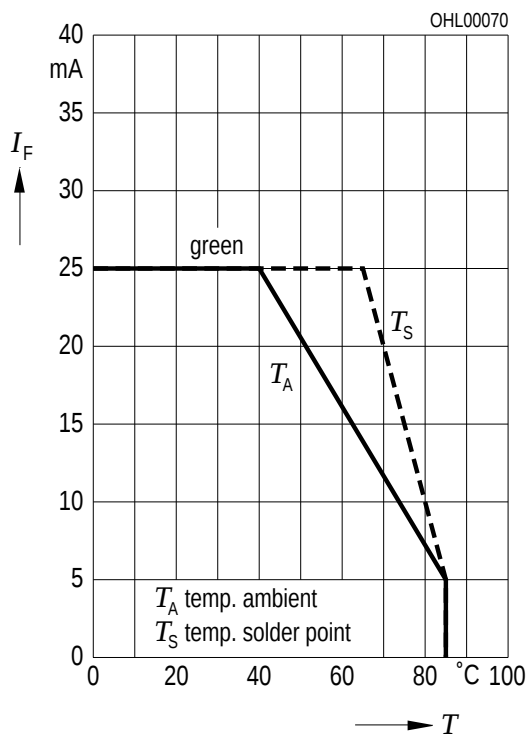
Relative Luminous Intensity

$T_A = 25\text{ °C}$



Maximal zulässiger Durchlassstrom $I_F = f(T_A)$

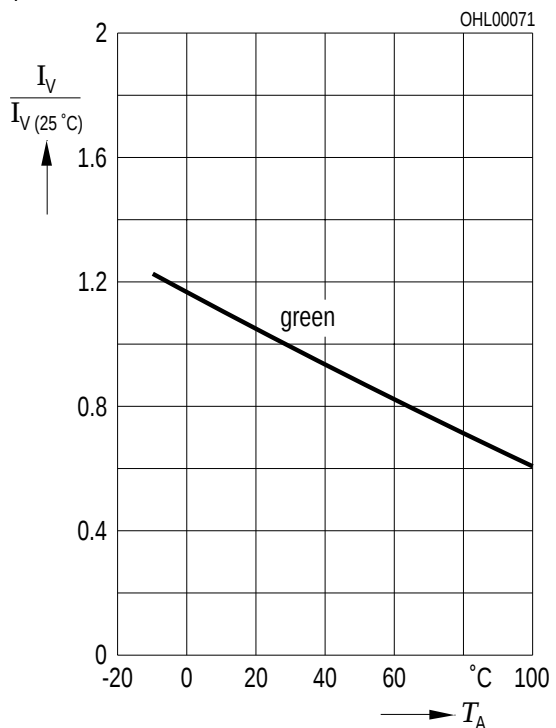
Max. Permissible Forward Current



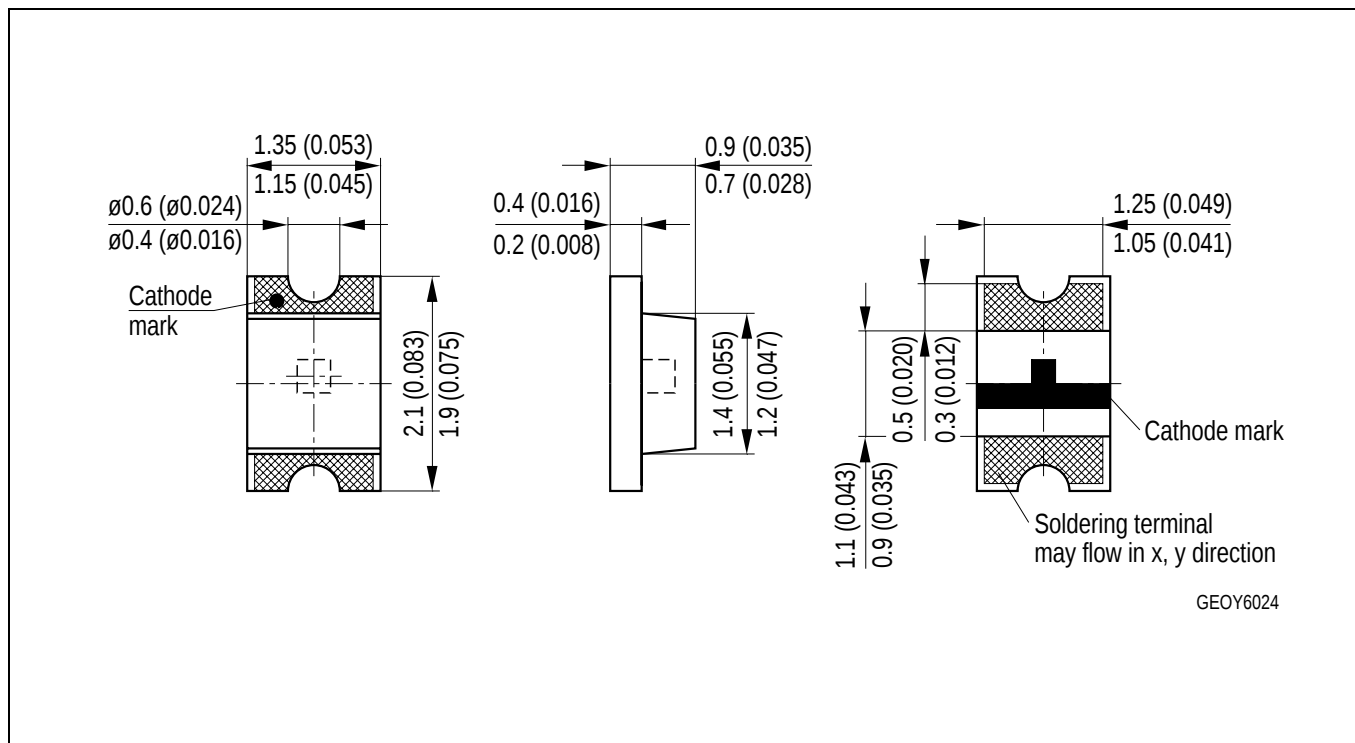
Relative Lichtstärke $I_V/I_{V(25\text{ °C})} = f(T_A)$

Relative Luminous Intensity

$I_F = 20\text{ mA}$



**Maßzeichnung
Package Outlines**

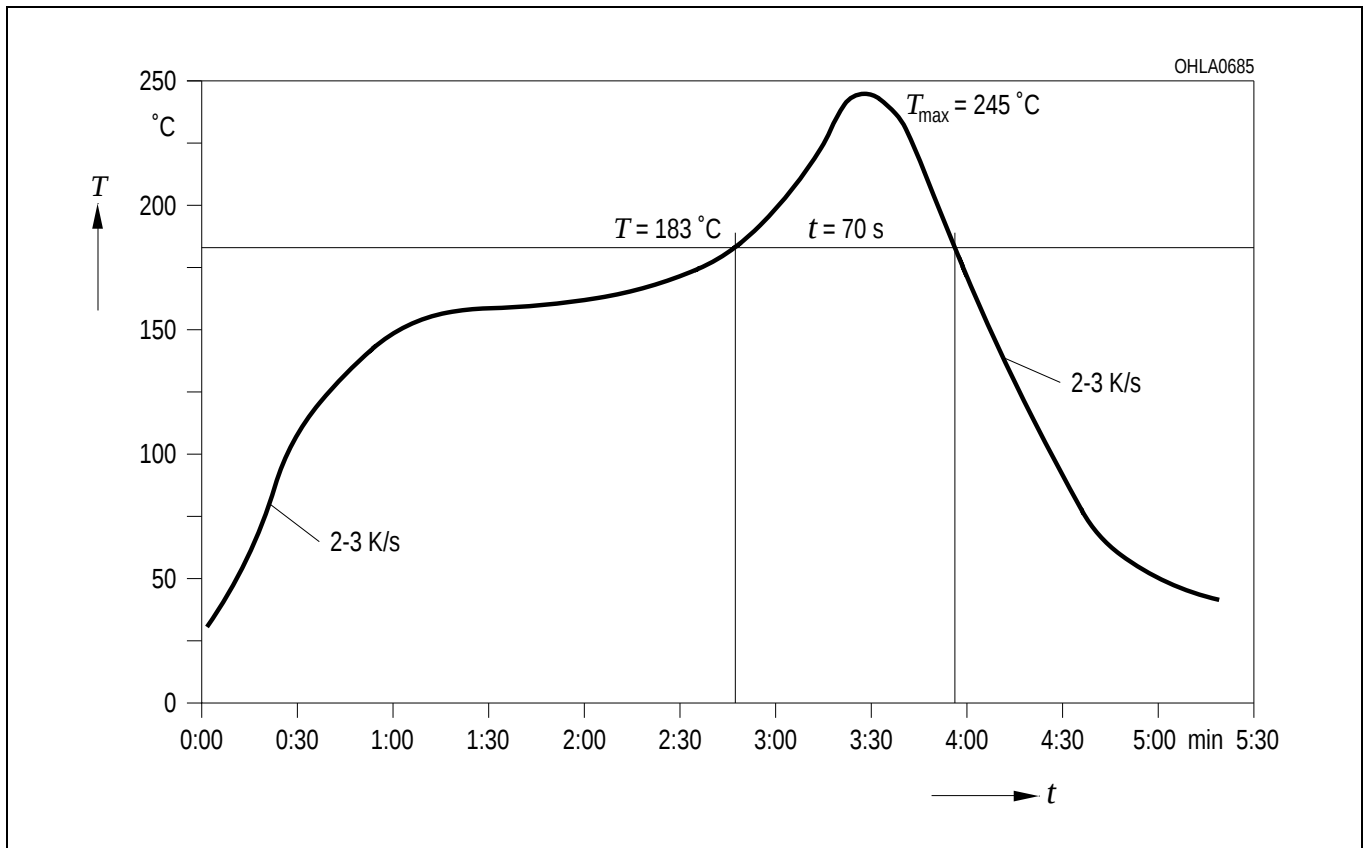


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

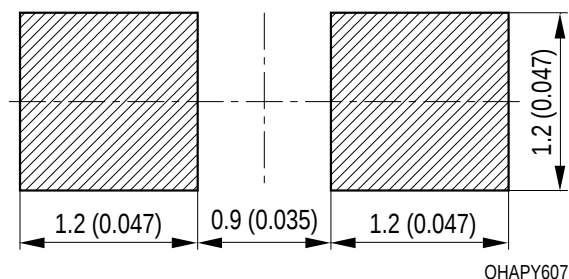
Gewicht / Approx. weight: 3.2 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)

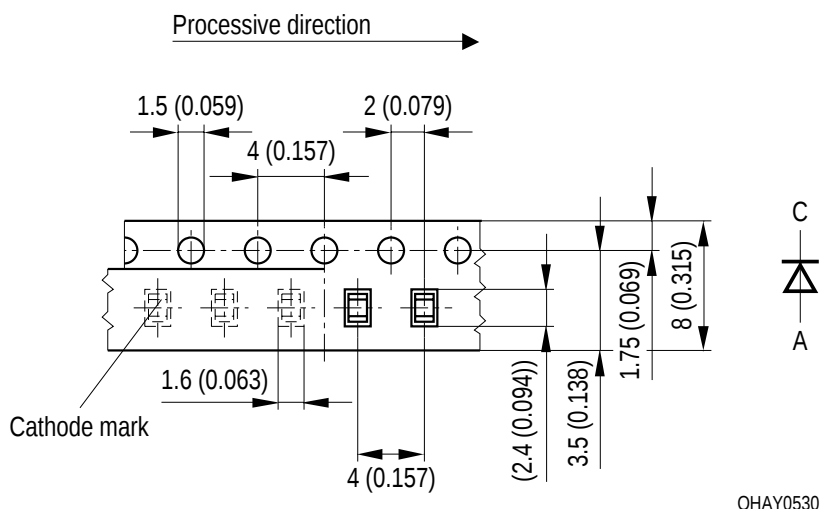


Empfohlenes Lötpaddesign IR Reflow Lötén
Recommended Solder Pad IR Reflow Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Gurtung / Polarität und Lage Verpackungseinheit 4000/Rolle, ø180 mm
Method of Taping / Polarity and Orientation Packing unit 4000/reel, ø180 mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2002-09-19		Date of change
Previous Version: 2002-08-19		
Page	Subjects (major changes since last revision)	
3	pad size from 16 mm ² to 5 mm ²	
11	annotations	2002-07-23
3, 4	value (reverse voltage from 5 V to 12 V)	2002-09-18
2	ordering code, wavelength group	2002-09-19

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Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose! Critical components ¹ may only be used in life-support devices or systems ² with the express written approval of OSRAM OS.

¹ A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

² Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.